This year ULTRA TEC Manufacturing, Inc. celebrates 50 years of business. Over this time we've seen the birth and growth of a number of high-tech industry sectors. We've supplied sample prep equipment to most of them. Over the years we have provided equipment that in some small way aided the growth of the fiber-optic backbone, mapping the human genome and the development of myriad optical, medical, analytical, and semiconductor products. We've helped engineers, reverse engineers, space scientists, smart card companies, game designers, police forces, service labs, and product developers not only to “Do their thing” but to “Do their thing BETTER!”

Our saws and polishers have been used throughout the semiconductor industry since the mid-1980s – seeing growth as our customers moved from manual polishing to semi-automatic polishing. The launch of the first ASAP-1 product in 1999 expanded our focus to enabling the FA sector’s move to backside analysis of the die.

Recent years have provided new challenges and opportunities, with the growth of mobile devices and the attendant need for faster, thinner, larger, smaller, 2D, 2.5D, and 3D IC devices.

As Moore's Law continues to be followed, bent, modified and exceeded, we would like to think there will always be an ULTRA TEC product at hand to help the FA Engineer figure out just what went wrong with their company’s IC.

For every EMMI, every SQUID, every FIB, every SIMS, every SIFT, every SIL … There’s an ULTRAPOL, ULTRASLICE or ASAP-1 ready to prepare your sample!

So, to our customers and friends – we thank you for your business and we look forward to joining you in meeting the technical challenges of the next 50 years together!

The ULTRA TEC Team